TOSHIBA INSULATED GATE BIPOLAR TRANSISTOR SILICON N CHANNEL IGBT

## GT30J322

# FOURTH-GENERATION IGBT CURRENT RESONANCE INVERTER SWITCHING APPLICATIONS

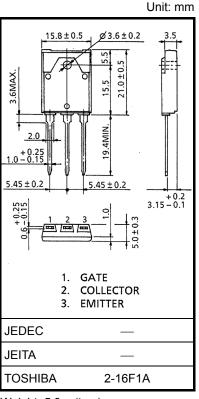
• FRD included between emitter and collector

• Enhancement mode type

• High speed :  $t_f = 0.25 \mu s$  (Typ.) (IC = 50A) • Low saturation voltage : VCE (sat) = 2.1V (Typ.) (IC = 50A)

#### ABSOLUTE MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT	
Collector-Emitter Voltage		V <sub>CES</sub>	600	V	
Gate-Emitter Voltage		V <sub>GES</sub>	±20	V	
Collector Current	DC	Ic	30	А	
	1ms	I <sub>CP</sub>	100		
Emitter-Collector Forward Current	DC	lF	30	Α	
	1ms	IFP	60	^	
Collector Power Dissipation (Tc = 25°C)		P <sub>C</sub>	75	W	
Junction Temperature		Tj	150	°C	
Storage Temperature Range		T <sub>stg</sub>	-55~150	°C	

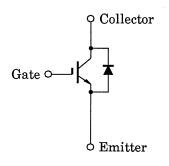


Weight: 5.8 g (typ.)

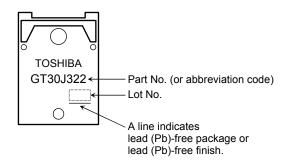
Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **EQUIVALENT CIRCUIT**



#### **MARKING**



### **ELECTRICAL CHARACTERISTICS (Ta = 25°C)**

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
Gate Leakage Current		I <sub>GES</sub>	V <sub>GE</sub> = ±20V, V <sub>CE</sub> = 0	_	_	±500	nA
Collector Cut-Off Current		I <sub>CES</sub>	V <sub>CE</sub> = 600V, V <sub>GE</sub> = 0	-	_	1.0	mA
Gate-Emitter Cut-Off Voltage		V <sub>GE</sub> (OFF)	I <sub>C</sub> = 50mA, V <sub>CE</sub> = 5V	3.0	_	6.0	V
Collector-Emitter Saturation Voltage		V <sub>CE</sub> (sat)	I <sub>C</sub> = 50A, V <sub>GE</sub> = 15V	_	2.1	2.8	V
Input Capacitance		C <sub>ies</sub>	V <sub>CE</sub> = 10V, V <sub>GE</sub> = 0, f = 1MHz	-	2500	_	pF
Switching Time	Rise Time	t <sub>r</sub>	15V 0 -15V 39Ω 300V	-	0.20	_	μs
	Turn-On Time	t <sub>on</sub>		-	0.30	_	
	Fall Time	t <sub>f</sub>		-	0.25	0.40	
	Turn-Off Time	t <sub>off</sub>		-	0.40	_	
Peak Forward Voltage		V <sub>F</sub>	I <sub>F</sub> = 30A, V <sub>GE</sub> = 0	-	_	2.0	V
Reverse Recovery Time		t <sub>rr</sub>	I <sub>F</sub> = 30A, V <sub>GE</sub> = 0 di / dt = -100A / µs	_	_	0.2	μs
Thermal Resistance (IGBT) Rth		R <sub>th (j-c)</sub>	IGBT	_	_	1.67	°C / W
Thermal Resistance (Diode)		R <sub>th (j-c)</sub>	Diode	1	_	2.27	°C / W